

L Number	Hits	Search Text	DB	Time stamp
-	412	(118/723i).CCLS.	USPAT; US-PGPUB	2002/05/10 13:06
-	240	(156/345.48).CCLS.	USPAT; US-PGPUB	2002/05/07 18:12
-	117	(118/723an).CCLS.	USPAT; US-PGPUB	2002/05/07 18:12
-	136	118/723i.ccls. and 156/345.48.ccls.	USPAT; EPO; JPO	2002/05/08 11:30
-	41	(118/723i.ccls. or 156/345.48.ccls. or 118/723an.ccls.) and ((Faraday adj shield))	USPAT; EPO; JPO	2002/05/08 11:31
-	10	("4659449" "5105761" "5134965" "5290993" "5401350" "5415728" "5522934" "5614055" "5753044" "5777289").PN.	USPAT	2002/05/08 11:50
-	5	("5681418" "5688357" "5688358" "5753044" "5777289").PN.	USPAT	2002/05/08 11:52
-	192	(118/723i.ccls. or 156/345.48.ccls. or 118/723an.ccls.) and (shield (Faraday adj shield))	USPAT; EPO; JPO	2002/05/08 11:57
-	59310	heat near5 (chamber reactor)	USPAT; EPO; JPO	2002/05/08 13:21
-	1	((resist\$3 adj heat\$3) near5 (chamber reactor)) and ((118/723i.ccls. or 156/345.48.ccls. or 118/723an.ccls.) and (shield (Faraday adj shield)))	USPAT; EPO; JPO	2002/05/08 13:23
-	384	(resist\$3 adj heat\$3) near5 (chamber reactor)	USPAT; EPO; JPO	2002/05/08 14:31
-	125	(resist\$3 adj heat\$3) near5 (chamber reactor) and (vapor adj deposition)	USPAT; EPO; JPO	2002/05/08 13:29
-	259	((resist\$3 adj heat\$3) near5 (chamber reactor)) not ((resist\$3 adj heat\$3) near5 (chamber reactor) and (vapor adj deposition))	USPAT; EPO; JPO	2002/05/08 14:05
-	12	4484063.URPN.	USPAT	2002/05/08 14:22
-	165	(heat\$3 adj wire) near5 (chamber reactor)	USPAT; EPO; JPO	2002/05/08 14:33
-	164	((heat\$3 adj wire) near5 (chamber reactor)) not ((resist\$3 adj heat\$3) near5 (chamber reactor))	USPAT; EPO; JPO	2002/05/08 16:03
-	1440	118/724.ccls.	USPAT; EPO; JPO	2002/05/08 16:21
-	30	118/724.ccls. and (heat\$3 adj wire)	USPAT; EPO; JPO	2002/05/09 08:49
-	12	4958592.URPN.	USPAT	2002/05/08 16:17
-	20	118/724.ccls. and 118/723i.ccls.	USPAT; EPO; JPO	2002/05/08 16:49
-	6	("5001113" "5365057" "5401350" "5556501" "5614055" "5865896").PN.	USPAT	2002/05/08 16:37
-	1085	c23c016/48.ipc.	EPO; JPO	2002/05/08 16:56
-	4	c23c016/48.ipc. and ((heat\$3 adj wire) (resistive adj heat) (resist\$ adj heat))	EPO; JPO	2002/05/08 16:51
-	15	c23c016/48.ipc. and "applied materials".as.	EPO; JPO	2002/05/08 16:57
-	4	5690050.URPN.	USPAT	2002/05/08 17:17
-	317	118/724.ccls. and (((heat\$3 adj element)(resist\$3 adj heat\$3) heat) near5 (chamber reactor))	USPAT; EPO; JPO	2002/05/09 10:09
-	109	156/345.37.ccls.	USPAT; EPO; JPO	2002/05/09 10:24
-	114	156/345.37.ccls.	USPAT; US-PGPUB; EPO; JPO	2002/05/09 14:22
-	1963	118/725.ccls.	USPAT; US-PGPUB; EPO; JPO	2002/05/09 14:23
-	23	118/725.ccls. and ((resist\$3 adj heat) (heat\$3 adj wire) near5 (substrate workpiece wafer))	USPAT; US-PGPUB; EPO; JPO	2002/05/09 14:26

-	6	118/725.ccls. and (((resist\$3 adj heat) (heat\$3 adj wire)) near5(substrate workpiece wafer))	USPAT; US-PGPUB; EPO; JPO	2002/05/09 14:30
-	389	(((resist\$3 adj heat) (heat\$3 adj wire)) near5(substrate workpiece wafer))	USPAT; US-PGPUB; EPO; JPO	2002/05/09 16:28
-	2	(h011021/\$.ipc. and c23c016/\$.ipc.) and (((resist\$3 adj heat) (heat\$3 adj wire)) near5(substrate workpiece wafer))	USPAT; US-PGPUB; EPO; JPO	2002/05/09 14:41
-	11	c23c016/\$.ipc. and (((resist\$3 adj heat) (heat\$3 adj wire)) near5(substrate workpiece wafer))	USPAT; US-PGPUB; EPO; JPO	2002/05/09 14:43
-	53	(h011021/\$.ipc.) and (((resist\$3 adj heat) (heat\$3 adj wire)) near5(substrate workpiece wafer))	USPAT; US-PGPUB; EPO; JPO	2002/05/09 14:55
-	7941	(substrate workpiece wafer) adj conductive	USPAT; US-PGPUB; EPO; JPO	2002/05/09 16:30
-	26835	(substrate workpiece wafer) near conductive	USPAT; US-PGPUB; EPO; JPO	2002/05/09 16:29
-	85726	vapor adj deposition	USPAT; US-PGPUB; EPO; JPO	2002/05/09 16:30
-	3206	(vapor adj deposition) and ((substrate workpiece wafer) near conductive)	USPAT; US-PGPUB; EPO; JPO	2002/05/09 16:30
-	2	156/345.48 and ((substrate workpiece wafer) adj conductive)	USPAT; US-PGPUB; EPO; JPO	2002/05/09 16:31
-	9	156/345.48 and ((substrate workpiece wafer) near conductive)	USPAT; US-PGPUB; EPO; JPO	2002/05/09 16:31
-	7	((("5690050") or ("5944899") or ("5735993") or ("6177646") or ("6095083") or ("5922223") or ("6077384")).PN. 219/121.43).CCLS.	USPAT; US-PGPUB	2002/05/10 13:17
-	314		USPAT; US-PGPUB	2002/05/10 13:18
-	1211	((156/345.37) or (156/345.48) or (118/723i) or (118/723an) or (118/723r)).CCLS.	USPAT; EPO; JPO	2003/01/16 13:56
-	128	((156/345.37) or (156/345.48) or (118/723i) or (118/723an) or (118/723r)).CCLS.) not @pd<=20020508	USPAT; EPO; JPO	2003/01/16 14:32
-	73	heat\$3 same (faraday adj shield)	USPAT; EPO; JPO	2003/01/16 14:33
-	98	heat\$3 same (faraday adj shield)	USPAT; EPO; JPO; DERWENT	2003/01/16 16:11
-	8	("5540800" "5650032" "5681418" "5685941" "5811022" "5903106" "5944899" "6280563").PN.	USPAT	2003/01/16 14:36
-	8	("5540800" "5650032" "5681418" "5685941" "5811022" "5903106" "5944899" "6280563").PN.	USPAT	2003/01/16 14:37
-	0	W000/52973	USPAT; EPO; JPO;	2003/01/16 16:12
-	0	00/52973	DERWENT USPAT;	2003/01/16 16:12
-	43	"52973"	EPO; JPO; DERWENT USPAT;	2003/01/16 16:23
-	135	holland-john\$.in.	EPO; JPO; DERWENT USPAT;	2003/01/16 16:24
-	6	li-maocheng\$.in.	EPO; JPO; DERWENT USPAT;	2003/01/16 16:25

-	9	todorov-valentin\$.in.	USPAT; EPO; JPO; DERWENT	2003/01/16 16:29
-	6	leahey-patrick\$.in.	USPAT; EPO; JPO; DERWENT	2003/01/16 16:31
-	7	hartlage-robert\$.in.	USPAT; EPO; JPO; DERWENT	2003/01/16 16:35
-	58	nguyen-hoan\$.in.	USPAT; EPO; JPO; DERWENT	2003/01/16 16:37
-	7657	"applied materials".as.	USPAT; EPO; JPO; DERWENT	2003/01/16 16:37
-	10	holland-john\$.in. and "applied materials".as.	USPAT; EPO; JPO; DERWENT	2003/01/16 16:37